EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	10	(US-20030032263-$ or US-20030006795-$ or US-20020194564-$ or US-20040195672-$).did. or (US-6237054-$ or US-5341096-$ or US-4728751-$ or US-6094736-$ or US-6263422-$ or US-5673276-$).did.	US-PGPUB; USPAT	OR	OFF	2007/07/28 16:51
L2	7	L1 and device with test$3	US-PGPUB; USPAT	OR	ON	2007/07/28 16:51
L3	3	L1 and (DUT device adj2 test)	US-PGPUB; USPAT	OR	OFF	2007/07/28 16:51
L4	3	L1 and under with test$3	US-PGPUB; USPAT	OR	ON	2007/07/28 16:51
L5	233	internal scan same boundary scan	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2007/07/28 16:51
L6	1891	(multi-chip package or MCP or multi-chip module or MCM) near3 (semiconductor or silicon)	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/07/28 16:51
L7	13	scan chain and L6	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/07/28 16:51
L8	54	interface with two-wire adj type	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 16:51
L9	28	boundary scan and L6	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/07/28 16:51
L10	1269	boundary scan test	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/07/28 16:51
L11	23	L10 and internal scan chain	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/07/28 16:51

L12	19	L11 and (board pcb mount mounting substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 16:51
L13	12	L12 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/28 16:51
L14	9	L13 and input terminal and output terminal	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/07/28 16:51
L15	24	(silicon semiconductor) same ceramic same (submount mount) same (TCE thermal adj coefficient)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 16:51
L16	149	L10 and internal scan	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/07/28 16:51
L17	134	L16 and (board pcb mount mounting substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 16:51
L18	104	L17 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/28 16:51
L19	21	IP Super-Sub	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2007/07/28 16:51
L20	3384	(714/724,726,727).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/07/28 16:51
L21	88	chip adj IP and IP	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 16:51
L22	364	L10 and L20	US-PGPUB; USPAT; USOCR	ADJ	OFF	2007/07/28 16:51

L23	43	L8 and (test tested testing tester test adj frame)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 16:51
L24	87	L18 and chip	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/28 16:51
L25	151	boundary scan and scan chain and IP	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2007/07/28 16:51
L26	113	L25 and (silicon semiconductor gaas inp)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 16:51
L27	113	L26 and (test tested testing tester test adj frame)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 16:51
L28	1334	(257/48).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/07/28 16:51
L29	58	chip adj IP and IP and intellectual adj property	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 16:51
L30	16	(US-20020194564-$ or US-20030006795-$ or US-20030032263-$ or US-20040195672-$ or US-20040197941-$ or US-20040199840-$ or US-20040221143-$).did. or (US-6094736-$ or US-4728751-$ or US-5673276-$ or US-6263422-$ or US-6237054-$ or US-6330666-$ or US-5383192-$ or US-5341096-$ or US-6734549-$).did.	US-PGPUB; USPAT	OR	OFF	2007/07/28 16:54
L31	1	(US-20040195672-$).did.	US-PGPUB	OR	OFF	2007/07/28 16:54
L32	1	L5 and L31	US-PGPUB; USPAT	OR	OFF	2007/07/28 16:54

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L33	4934	(internal or boundary) scan	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2007/07/28 16:54
L34	1	L33 and L31	US-PGPUB; USPAT	OR	OFF	2007/07/28 16:54